ABSTRACT OF THE DISCLOSURE

A method of manufacturing an electronic circuit satisfying demands for cost reduction, diversified small-quantity production, and a shorter cycle of design, manufacture, evaluation, correction, and so on is provided. The method includes at least forming a first pattern or forming a second pattern. Forming the first pattern comprises: forming a visible image on an electrostatic latent image formed on a photosensitive base , by the adhesion of charged particles essentially made of a resin; transferring the visible image onto the intermediate transfer base by the contact and pressurization of the visible image; heating/softening on the intermediate transfer base; and transferring a heated/softened resin layer onto a base material by the contact and pressurization of the resin layer. In forming the second pattern, using charged particles containing conductive metal particulates, a conductor metal layer is formed by electroless plating after a metal-containing resin pattern is transferred similarly to the first pattern formation.